



APTPEP1.40CP2DC (formerly APTLTD.40CP2DC)

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Gerald A. Hutchinson, et. al
Appl. No. : 10/788,905
Filed : February 26, 2004
For : PREFORM MOLDS
INCORPORATING HIGH HEAT
CONDUCTIVITY MATERIAL
Examiner : Timothy W. Heitbrink

Group Art Unit 1722

AMENDMENT AND RESPONSE TO JANUARY 30, 2006 OFFICE ACTION

Mail Stop Amendment
U.S. Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the January 30, 2006 Office Action, Applicant requests the Examiner to reconsider the above-identified patent application in view of the following amendments and remarks.

Amendments to the Claims: Begin on page 2 of this Response.

Remarks: Begin on page 6 of this Response.